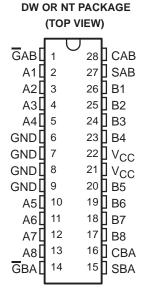


- EPIC™ (Enhanced-Performance Implanted CMOS) 1-μm Process
- 500-mA Typical Latch-Up Immunity at 125°C
- Package Options Include Plastic Small Outline Packages and Standard Plastic 300-mil DIPs



description

These devices consist of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the data bus or from the internal storage registers. Enables GAB and $\overline{G}BA$ are provided to control the transceiver functions. SAB and SBA control pins are provided to select whether real-time or stored data is transferred. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data.

A low input level selects real-time data and a high selects stored data. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the octal bus transceivers and registers. Data on the A or B bus, or both, can be stored in the internal D flip-flops by low-to-high transitions at the appropriate clock pins (CAB or CBA) regardless of the select or enable control pins. When SAB and SBA are in the real-time transfer mode, it is also possible to store data without using the internal D-type flip-flops by simultaneously enabling GAB and GBA. In this configuration, each output reinforces its input. Thus, when all other data sources to the two sets of bus lines are at high impedance, each set of bus lines remains at its last state.

The 74ACT11651 is characterized for operation from – 40°C to 85°C.

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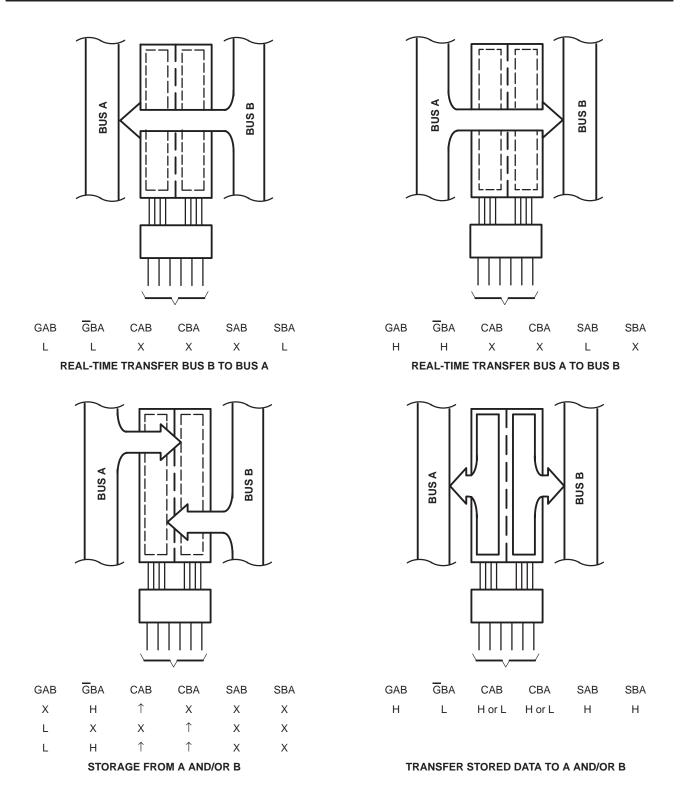


Figure 1. Bus Transfer Diagram

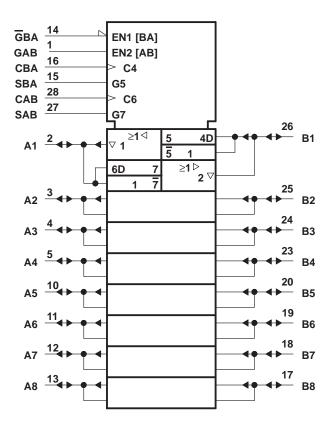


FUNCTION TABLE

		INP	UTS			DAT	DATA I/O		
GAB	GBA	CAB	CBA	SAB	SBA	A1 THRU A8	B1 THRU B8	OPERATION OR FUNCTION	
L	Н	H or L	H or L	Х	Х	Input	Input	Isolation	
L	Н	\uparrow	↑	Х	Х	Input	Input	Store A and B Data	
X	Н	↑	H or L	Х	Х	Input	Unspecified [†]	Store A, Hold B	
Н	Н	↑	↑	χ‡	Х	Input	Output	Store A in both registers	
L	Х	H or L	↑	Х	Х	Unspecified [†]	Input	Hold A, Store B	
L	L	↑	↑	Х	X‡	Output	Input	Store B in both registers	
L	L	Х	Х	Х	L	Output	Input	Real-Time B data to A Bus	
L	L	Х	H or L	Х	Н	Output	Input	Stored B Data to A Bus	
Н	Н	Х	Х	L	Х	Input	Output	Real-Time A Data to B Bus	
Н	Н	H or L	X	Н	Х	Input	Output	Stored \overline{A} Data to B Bus	
Н	L	H or L	H or L	Н	Н	Output	Output	Stored A Data to B Bus and	
								Stored B Data to A Bus	

[†] The data output functions may be enabled or disabled by various signals at the GAB or GBA inputs. Data input functions are always enabled, i.e., data at the bus pins will be stored on every low-to-high transition on the clock inputs.

logic symbol§

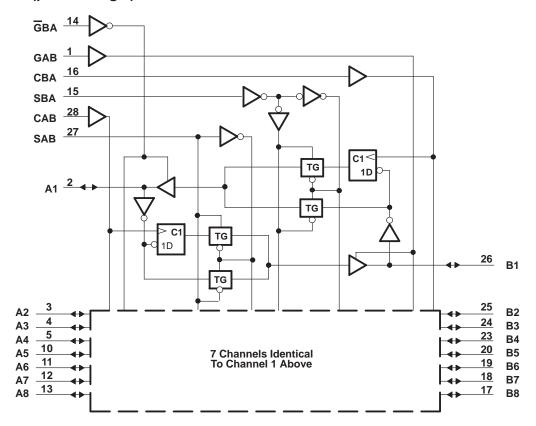


§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



[‡] Select control = L: clocks can occur simultaneously. Select control = H: clocks must be staggered in order to load both registers.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	– 0.5 V to V_{CC} + 0.5 V
Output voltage range, V _O (see Note 1)	– 0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$)	± 20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC})	± 50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	± 50 mA
Continuous current through V _{CC} or GND	± 200 mA
Storage temperature range	– 65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output voltage ratings may be exceeded if the input and output current ratings are observed.



recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
VIH	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
VI	Input voltage	0		VCC	V
VO	Output voltage	0		VCC	V
IOH	High-level output current			-24	mA
loL	Low-level output current			24	mA
Δt/Δν	Input transition rise or fall rate	0		10	ns/V
TA	Operating free-air temperature	-40		85	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

-	D.4.4.ETED	TEGT COMPLETIONS	,,	T,	4 = 25°C	;		MAY	
PARAMETER		TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
		I 50 A	4.5 V	4.4			4.4		
		I _{OH} = – 50 μA	5.5 V	5.4			5.4		
Voн		04 ***	4.5 V	3.94			3.8		V
		I _{OH} = – 24 mA	5.5 V	4.94			4.8		
		I _{OH} = - 75 mA [†]	5.5 V				3.85		
		L 50 A	4.5 V			0.1		0.1	V
		I _{OL} = 50 μA	5.5 V			0.1		0.1	
VOL		044	4.5 V			0.36		0.44	
		I _{OL} = 24 mA	5.5 V			0.36		0.44	
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
loz	A or B ports§	V _I = V _{CC} or GND	5.5 V			± 0.5		± 5	μΑ
lį	Control Inputs	V _I = V _{CC} or GND	5.5 V			± 0.1		± 1	μΑ
Icc		$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			8		80	μΑ
Δl _{CC} ‡	•	$V_I = V_{CC}$ or GND	5.5 V			0.9		1	mA
Ci	Control Inputs	$V_I = V_{CC}$ or GND	5 V		4.5				pF
C _{io}	A or B ports	$V_I = V_{CC}$ or GND	5 V		10				pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

		T _A = 1	25°C	BAINI	MAX	UNIT
		MIN	MAX	MIN	WAX	UNII
fclock	Clock frequency	0	90	0	100	MHz
t _W	Pulse duration, CAB or CBA high or low	5.5		5		ns
t _{su}	Setup time, A before CAB↑ or B before CBA↑	4.5		4.5		ns
th	Hold time, A after CAB↑ or B after CBA↑	2		0		ns



[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

 $[\]mbox{\ensuremath{\,\$}}\mbox{ For I/O}$ ports, the parameter $\mbox{\ensuremath{\,\text{IOZ}}}\mbox{ includes the input leakage current.}$

74ACT11651 OCTAL BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 2)

24244555	FROM	то	T,	ղ = 25°C	;	BAIN! BAIN	LINUT	
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	UNIT
f _{max}			90			90		MH_Z
^t PLH	A on D	D on A	2.6	5.6	8.9	2.6	9.9	
^t PHL	A or B	B or A	4.7	7.7	10.7	4.7	11.9	ns
^t PLH	ODA OAD	A su D	5.5	8.4	11.2	5.5	12.7	
^t PHL	CBA or CAB	A or B	6.3	9.5	12.7	6.3	14.1	ns
^t PLH	SBA or SAB†		4.8	7.6	10.4	4.8	11.8	
^t PHL	with A or B high	A or B	4.1	7.7	11.2	4.1	12.4	ns
^t PLH	SBA or SAB†	Λ Αν D	3	6.2	9.3	3	10.4	
^t PHL	with A or B low		5.6	8.7	11.7	5.6	13	ns
^t PZH	- GBA		4	7.4	10.7	4	11.9	
t _{PZL}	GBA	А	4.3	8.2	11.9	4.3	13.3	ns
^t PHZ	- G BA		5.9	7.7	9.5	5.9	10	
^t PLZ	GBA	A	5.1	6.9	8.7	5.1	9.2	ns
^t PZH	OAR	_	5.9	9	12.1	5.9	13.7	
t _{PZL}	GAB	В	6.4	9.8	13.2	6.4	14.9	ns
^t PHZ	GAB	В	4.7	7.1	9.5	4.7	10	20
^t PLZ	GAB		3.8	6.1	8.4	3.8	8.8	ns

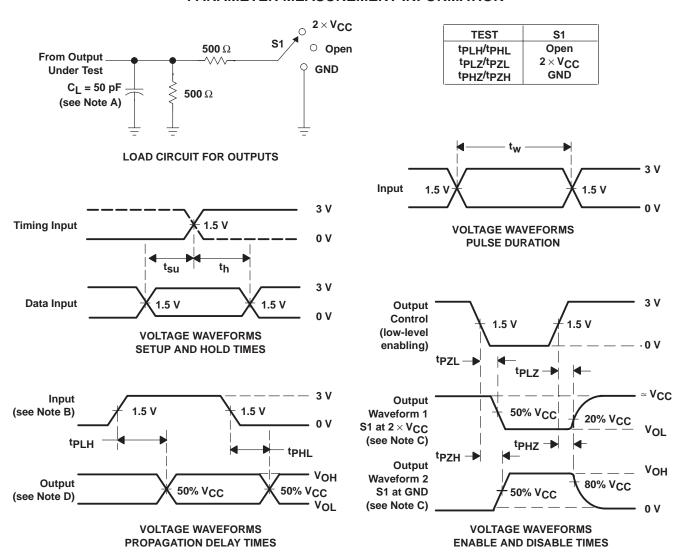
[†] These parameters are measured with the internal output state of the storage register opposite to that of the bus input.

operating characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

	PARAMETER	TEST CONDITIO	NS	TYP	UNIT	
		Outputs enabled	0 50 5 (4.841.1	61	_
Cpd	Power dissipation capacitance per gate	Outputs disabled	$C_L = 50 \text{ pF}, \qquad f =$	1 MHz	15	pF



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns. For testing pulse duration: $t_f = t_f = 1$ to 3 ns. Pulse polarity can be either high-to-low-to-high or low-to-high-to-low.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 2. Load Circuit and Voltage Waveforms







ti.com 24-Jun-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ACT11651DW	OBSOLETE	SOIC	DW	28	TBD	Call TI	Call TI
74ACT11651NT	OBSOLETE	PDIP	NT	28	TBD	Call TI	Call TI
74ACT11651NT	OBSOLETE	PDIP	NT	28	TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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		Wireless	www.ti.com/wireless-apps